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2823

DOCKET NO.: CHITTIPEDDI 59-108

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Sailish Chittipeddi, *et al.*

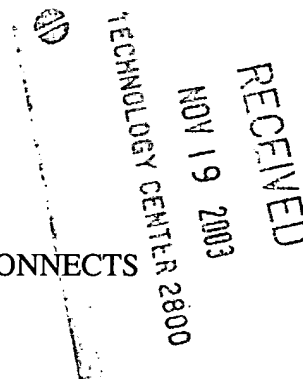
Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313, on	
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(Signature of the person signing the certificate)	

Sir:

AMENDMENT UNDER 37 C.F.R. § 1.111

In response to the Examiner's Action mailed August 21, 2003, please consider the following remarks: